Special Issue

Additive Manufacturing of Copper-Based Alloys

Message from the Guest Editor

Metal additive manufacturing (AM) has become a critical facet of the global advanced manufacturing enterprise. Copper-rich alloys feature prominently in this regard due to useful traits that include high electrical conductivity, exceptional strength, and outstanding corrosion resistance depending on the alloy system in question. This Special Issue seeks to publish fundamental and applied research related to the AM of these materials. Focal areas of interest include (but are not limited to) the following:

- Production of feedstock materials for copper AM processing;
- Copper alloy development for AM;
- Processing of conventional copper alloy chemistries using AM;
- Directed energy deposition of copper-rich alloys;
- Laser powder bed fusion of copper-rich alloys;
- Binder jet printing of copper-rich alloys;
- Wire arc additive manufacturing of copper-rich alloys;
- Properties of copper alloys processed through AM;
- Use of non-conventional approaches and/or energy sources in the AM of copper alloys;
- Effects of secondary operations on copper AM products;
- Commercialized applications for copper AM products.

Guest Editor

Prof. Dr. Paul Bishop

Net Shape Manufacturing Group, Department of Mechanical Engineering, Dalhousie University, Halifax, NS B3H 4R2, Canada

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Journal of Manufacturing and Materials Processing
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
jmmp@mdpi.com

mdpi.com/journal/jmmp

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About the Journal

Message from the Editor-in-Chief

Journal of Manufacturing and Materials Processing (*JMMP*)(ISSN 2504-4494) is a new MDPI peer-reviewed, open access venue with a focus on the scientific fundamentals and engineering methodologies of manufacturing and materials processing. We offer an online platform facilitating effective exchange of innovative scientific and engineering ideas and the dissemination of recent, original, and significant research and developmental findings. On behalf of the Editorial Board, I extend an invitation to our scientific and engineering colleagues to contribute high-quality, innovative, and ground-breaking research articles to *JMMP.*

Editor-in-Chief

Prof. Dr. Steven Y. Liang
George W. Woodruff School of Mechanical Engineering, Georgia Institute of Technology, Atlanta, GA 30332-0405, USA

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